



# **RFBPF Series – 1608(0603)- RoHS Compliance**

# MULTILAYER CERAMIC BAND PASS FILTER

## Halogens Free Product

2.4 GHz ISM Band Working Frequency

# P/N: RFBPF1608070A3T

\*Contents in this sheet are subject to change without prior notice.

#### **Approval sheet**

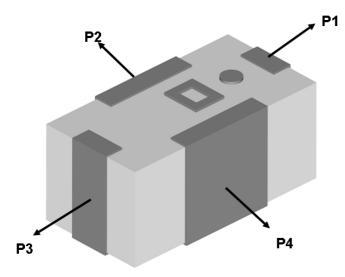


- 1. Miniature footprint: 1.6 X 0.8 X 0.7 mm<sup>3</sup>
- 2. Low Profile Thickness
- 3. Low Insertion loss
- 4. High Rejection Rate
- 5. High attenuation on 2<sup>nd</sup> harmonic suppressed
- 6. LTCC process

#### APPLICATIONS

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless LAN 802.11b/g, HomeRF

#### CONSTRUCTION



PIN	Connection		
1	Input port		
2	GND		
3	Output port		
4	GND		

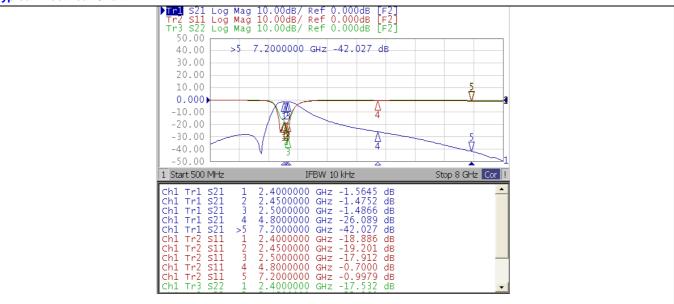
#### DIMENSIONS

Figure	Symbol	Dimension (mm)
	L	1.60 ± 0.15
	W	0.80 ± 0.15
	т	0.70 ± 0.10
	A	0.45 ± 0.15
	В	0.70 ± 0.15
	С	0.20 ± 0.15
	D	0.20 ± 0.15
	E	0.25 ± 0.15
	F	0.30 ± 0.15

#### ELECTRICAL CHARACTERISTICS

RFBPF1608070A3T	Specification
Frequency range	2450 ± 50 MHz
Insertion Loss	1.80 dB max. at 25 ℃ 2.10 dB max. at – 40 ~ + 85 ℃
VSWR	2.0 max
Impedance	50 Ω
	27 dB @ 800 – 900 MHz
Attenuation (min.)	25 dB @ 4800-5000 MHz
	30 dB @ 7200-7500 MHz
Operation Temperature Range	-40°C ~ +85°C

#### **Typical Electrical Chart**



#### SOLDER LAND PATTERN

Figure	Symbol	Dimension (mm)			
	L1	1.40 ± 0.10			
	L2	0.80 ± 0.05			
	L3	0.50 ± 0.05			
	L4	0.64 ± 0.05			
	L5	0.37 ± 0.05			
	W1	0.94 ± 0.10			
	W2	0.70 ± 0.05			
	W3	0.43 ± 0.05			
	D1	0.30 ± 0.05			
	D2	0.35 ± 0.05			
	S1	0.35 ± 0.05			
Line width to de designed to match 50 $\Omega$ characteristic impedance, depending on PCB material and thickness.					

D1 and D2 are the grounding through holes.



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#### RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability	*Solder bath temperature : $235 \pm 5^{\circ}C$	At least 95% of a surface of each terminal
JIS C 0050-4.6 JESD22-B102D	*Immersion time : $2 \pm 0.5$ sec	electrode must be covered by fresh solder.
	*Solder:Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization)	*Solder bath temperature : $260 \pm 5$ °C *Leaching immersion time : $30 \pm 0.5$ sec	Loss of metallization on the edges of each electrode shall not exceed 25%.
IEC 60068-2-58	*Solder : SN63A	
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature ÷ 120~150℃, 1 minute.	No mechanical damage. Samples shall satisfy electrical specification
	*Solder temperature : 270±5°C	after test.
	*Immersion time : 10±1 sec	Loss of metallization on the edges of each electrode shall not exceed 25%.
	*Solder : Sn3Ag0.5Cu for lead-free	
	Measurement to be made after keeping at room temperature for 24±2 hrs	
Drop Test JIS C 0044	<ul> <li>*Height : 75 cm</li> <li>*Test Surface : Rigid surface of concrete or steel.</li> <li>*Times : 6 surfaces for each units ; 2 times for each side.</li> </ul>	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec.	No mechanical damage. Samples shall satisfy electrical specification after test.
	Measurement to be made after keeping at room temperature for 24±2 hours	

### **PSA** 華新科技股份有限公司 Walsin Technology Corporation

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Temperature cycle JIS C 0025	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency : 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude : 1.5mm	Samples shall satisfy electrical specification
	*Test times : 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature	*Temperature : 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time:1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	⅔ 500hrs measuring the first data then	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	

#### SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

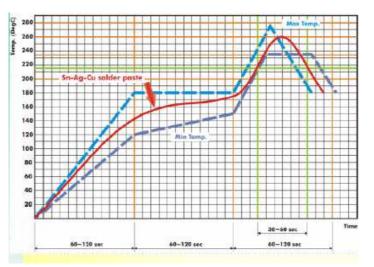


Fig 2. Infrared soldering profile

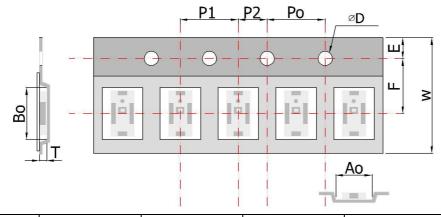
#### ORDERING CODE

RF	BPF	160807	0	Α	3	Т
Walsin	Product Code	Dimension code	Unit of	Application	Specification	Packing
RG: RF	BPF :	Per 2 digits of	dimension	A : 2.4GHZ ISM	Code from 0 ~ 9	T: Reeled
/Pb free	Band Pass Filter	Length, Width,	0 : 0.1 mm	Band	dependent on	
device		Thickness :	1 : 1.0 mm		different electrical	
		e.g. :			specification	
		160807 =				
		Length 16,				
		Width 08,				
		Thickness07				

Minimum Ordering Quantity: 4000 pcs per reel.

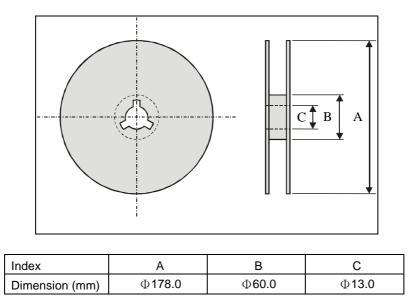
#### PACKAGING

Paper Tape specifications (unit :mm)



Index	Ao	Во	ΦD	Т	W
Dimension (mm)	$0.975\pm0.05$	$1.76\pm0.05$	1.55 + 0.05	$0.75\pm0.03$	$8.0\pm0.10$
Index	E	F	Po	P1	P2
Dimension (mm)	$1.75\pm0.10$	$3.50\pm0.05$	$4.00\pm0.10$	$4.00\pm0.10$	$2.00\pm0.05$

#### **Reel dimensions**



Taping Quantity: 4000 pieces per 7" reel

#### CAUTION OF HANDLING

#### Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

#### Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
  - Products should be storage in the warehouse on the following conditions.
  - Temperature : -10 to +40°C
  - Humidity : 30 to 70% relative humidity
  - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
  - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
  - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
  - Products should be storage under the airtight packaged condition.